

30V N-Channel NexFET™ Power MOSFETs

Check for Samples: [CSD17555Q5A](#)

FEATURES

- Ultralow Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5-mm × 6-mm Plastic Package

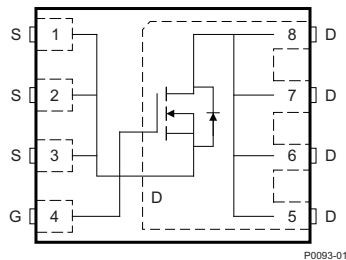
APPLICATIONS

- Point-of-Load Synchronous Buck in Networking, Telecom, and Computing Systems
- Optimized for Control and Synchronous FET Applications

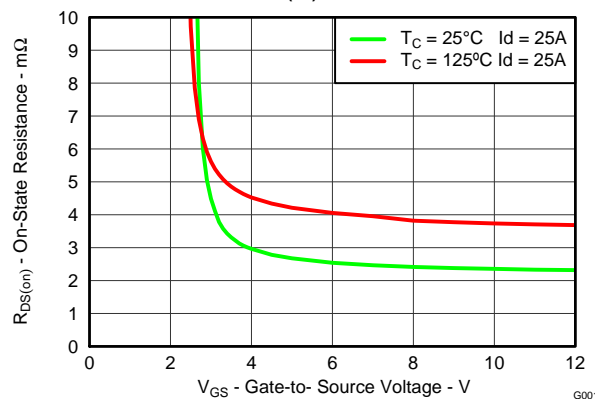
DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.

Top View



P0093-01

 $R_{DS(on)}$ vs V_{GS}


G001

PRODUCT SUMMARY

$T_A = 25^\circ\text{C}$ unless otherwise stated		TYPICAL VALUE	UNIT
V_{DS}	Drain to Source Voltage	30	V
Q_g	Gate Charge Total (4.5V)	23	nC
Q_{gd}	Gate Charge Gate to Drain	5	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5\text{V}$	2.8 mΩ
		$V_{GS} = 10\text{V}$	2.3 mΩ
$V_{GS(th)}$	Threshold Voltage	1.5	V

ORDERING INFORMATION

Device	Package	Media	Qty	Ship
CSD17555Q5A	SON 5-mm × 6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

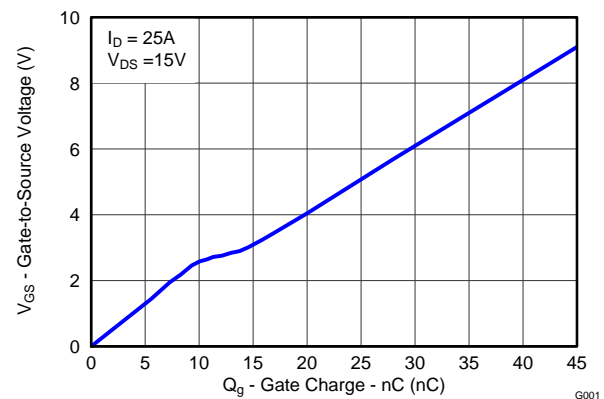
ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Continuous Drain Current (Package limited), $T_C = 25^\circ\text{C}$	100	A
	Continuous Drain Current (Silicon limited), $T_C = 25^\circ\text{C}$	116	
	Continuous Drain Current ⁽¹⁾	24	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ ⁽²⁾	153	A
P_D	Power Dissipation ⁽¹⁾	3	W
T_J , T_{STG}	Operating Junction and Storage Temperature Range	–55 to 150	°C
E_{AS}	Avalanche Energy, single pulse $I_D = 60\text{A}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$	180	mJ

(1) Typical $R_{\theta JA} = 42^\circ\text{C/W}$ on 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.

(2) Pulse duration ≤300μs, duty cycle ≤2%

GATE CHARGE



G001



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise stated)

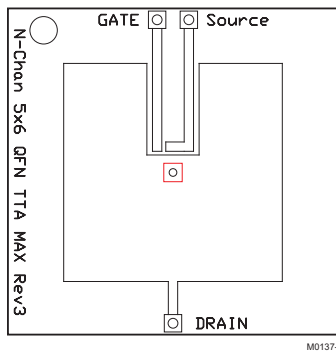
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Static Characteristics							
BV _{DSS}	Drain to Source Voltage	V _{GS} = 0V, I _{DS} = 250μA	30			V	
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 24V			1	μA	
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = 20V			100	nA	
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250μA	1	1.5	1.9	V	
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 4.5V, I _{DS} = 25A			2.8	3.4	mΩ
		V _{GS} = 10V, I _{DS} = 25A			2.3	2.7	mΩ
g _{fs}	Transconductance	V _{DS} = 15V, I _{DS} = 25A	109			S	
Dynamic Characteristics							
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	3875		4650	pF	
C _{oss}	Output Capacitance		949		1139	pF	
C _{rss}	Reverse Transfer Capacitance		70		87	pF	
R _G	Series Gate Resistance	V _{DS} = 15V, I _{DS} = 25A	0.8		1.6	Ω	
Q _g	Gate Charge Total (4.5V)		23		28	nC	
Q _{gd}	Gate Charge Gate to Drain		5			nC	
Q _{gs}	Gate Charge Gate to Source		7.5			nC	
Q _{g(th)}	Gate Charge at V _{th}		5			nC	
Q _{oss}	Output Charge	V _{DS} = 14V, V _{GS} = 0V	25			nC	
t _{d(on)}	Turn On Delay Time	V _{DS} = 15V, V _{GS} = 4.5V, I _{DS} = 25A,R _G = 2Ω	14			ns	
t _r	Rise Time		18			ns	
t _{d(off)}	Turn Off Delay Time		20			ns	
t _f	Fall Time		5.3			ns	
Diode Characteristics							
V _{SD}	Diode Forward Voltage	I _{SD} = 25A, V _{GS} = 0V	0.8		1	V	
Q _{rr}	Reverse Recovery Charge	V _{DD} = 14V, I _F = 25A, di/dt = 300A/μs	31			nC	
t _{rr}	Reverse Recovery Time		25			ns	

THERMAL CHARACTERISTICS

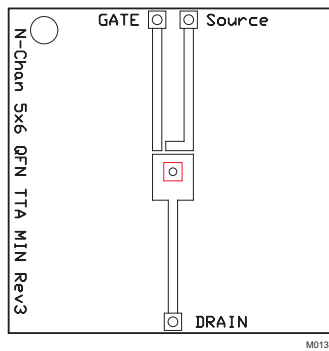
($T_A = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case ⁽¹⁾			2.2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ⁽¹⁾⁽²⁾			52	$^\circ\text{C/W}$

- (1) $R_{\theta JC}$ is determined with the device mounted on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch × 1.5-inch (3.81-cm × 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB. $R_{\theta JC}$ is specified by design, whereas $R_{\theta JA}$ is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.



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M0137-02

TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^{\circ}\text{C}$ unless otherwise stated)

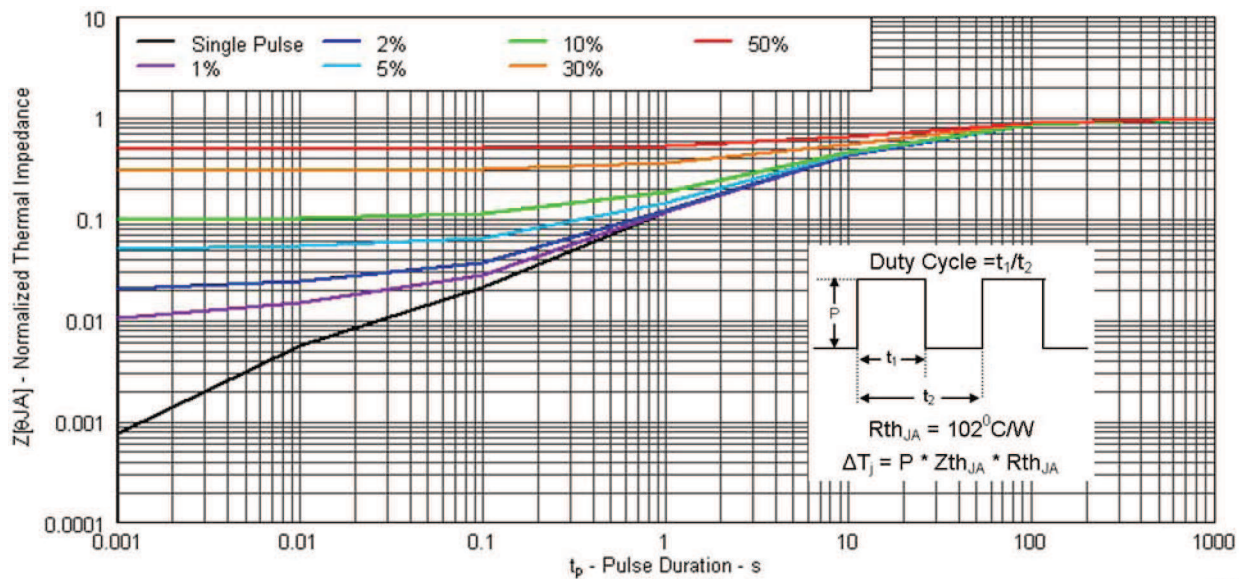


Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

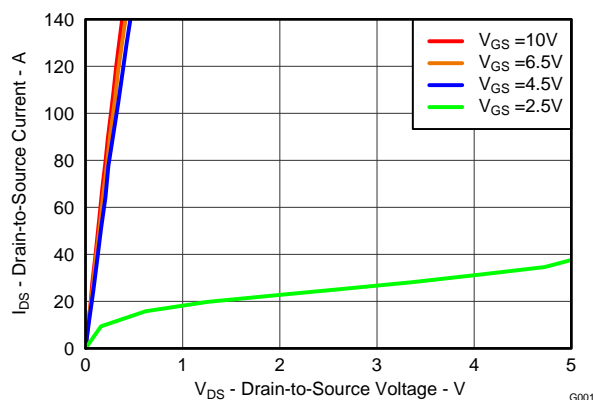


Figure 2. Saturation Characteristics

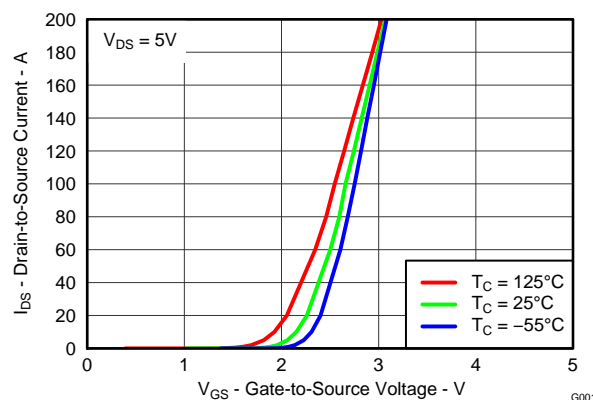


Figure 3. Transfer Characteristics

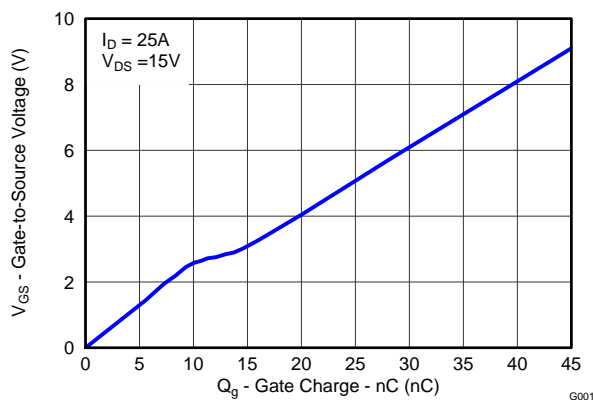


Figure 4. Gate Charge

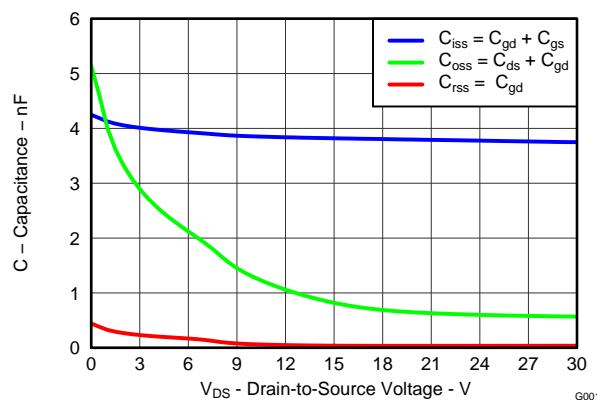


Figure 5. Capacitance

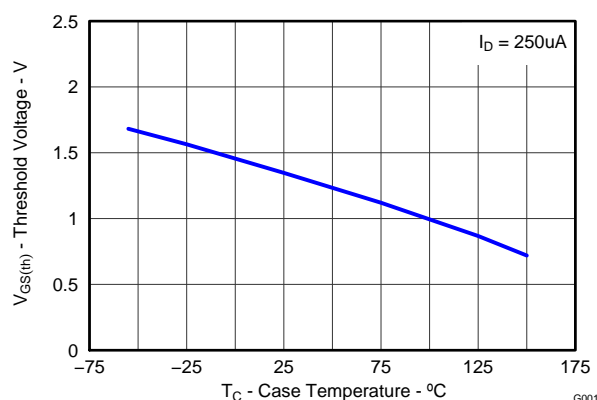


Figure 6. Threshold Voltage vs. Temperature

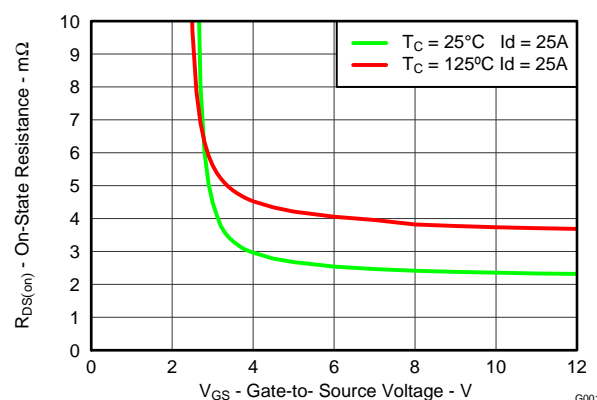


Figure 7. On-State Resistance vs. Gate-to-Source Voltage

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

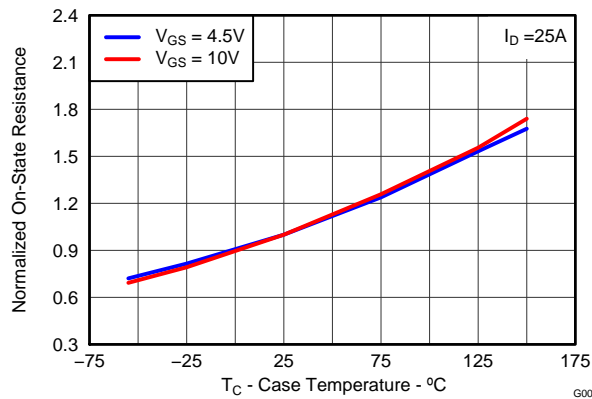


Figure 8. Normalized On-State Resistance vs. Temperature

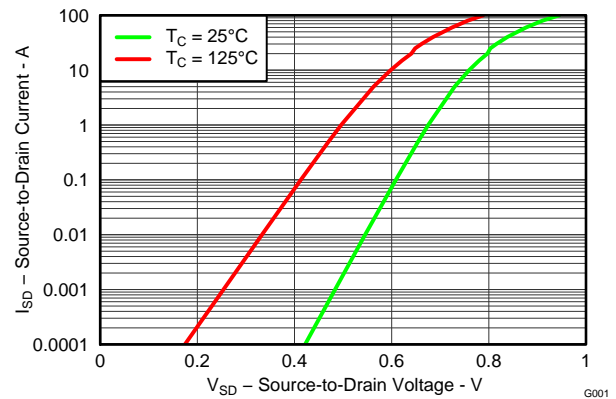


Figure 9. Typical Diode Forward Voltage

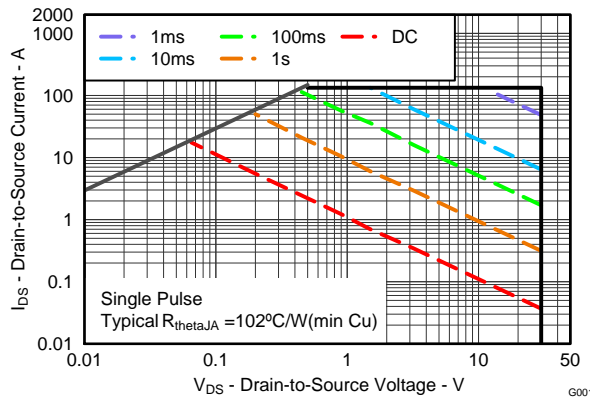


Figure 10. Maximum Safe Operating Area

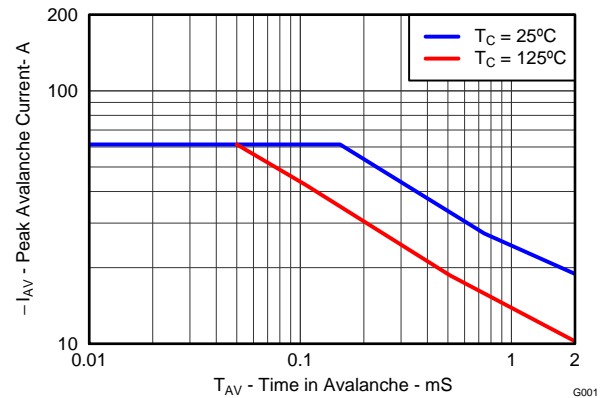


Figure 11. Single Pulse Unclamped Inductive Switching

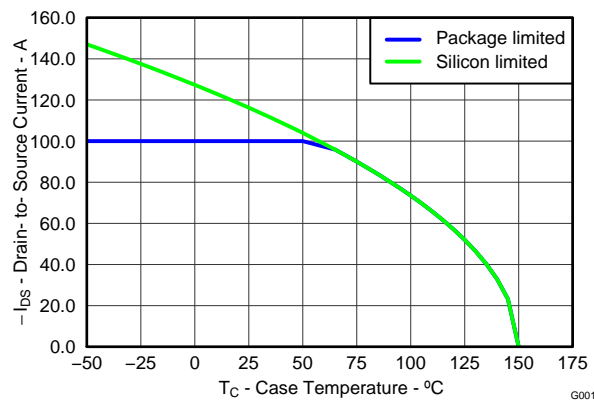
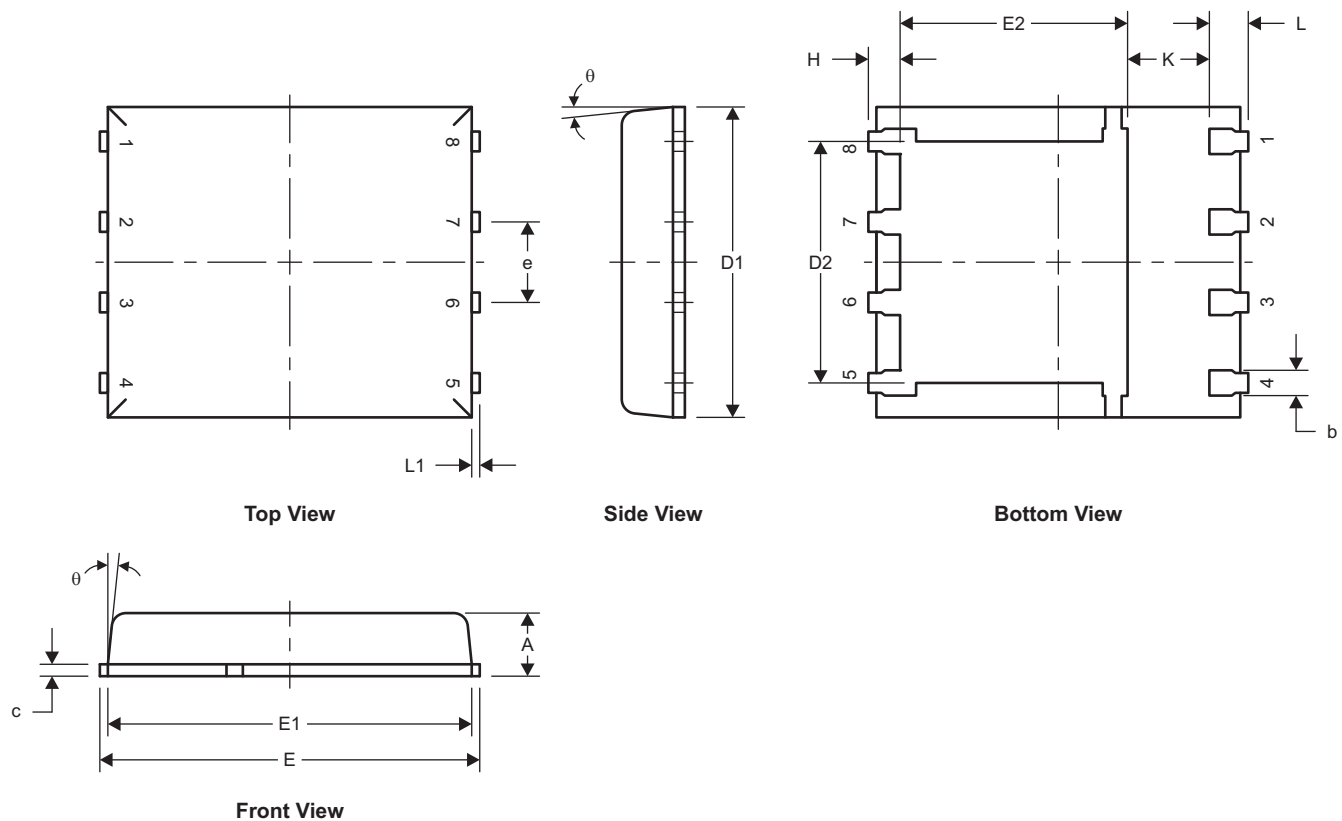


Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA

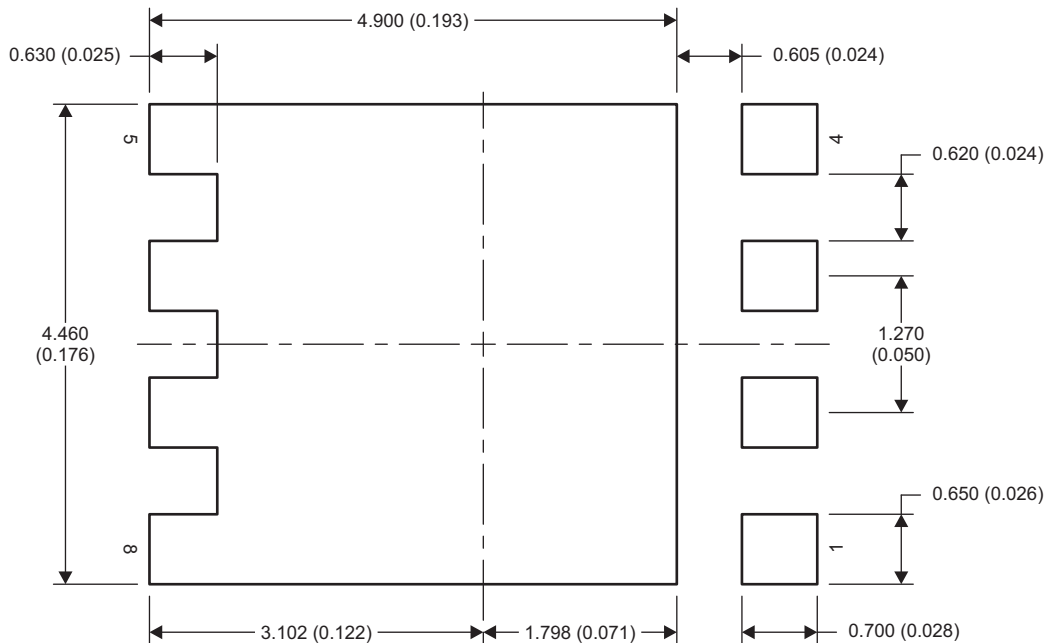
Q5A Package Dimensions



M0135-01

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.33	0.41	0.51
c	0.20	0.25	0.34
D1	4.80	4.90	5.00
D2	3.61	3.81	4.02
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.17	1.27	1.37
H	0.41	0.56	0.71
K	1.10		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
θ	0°		12°

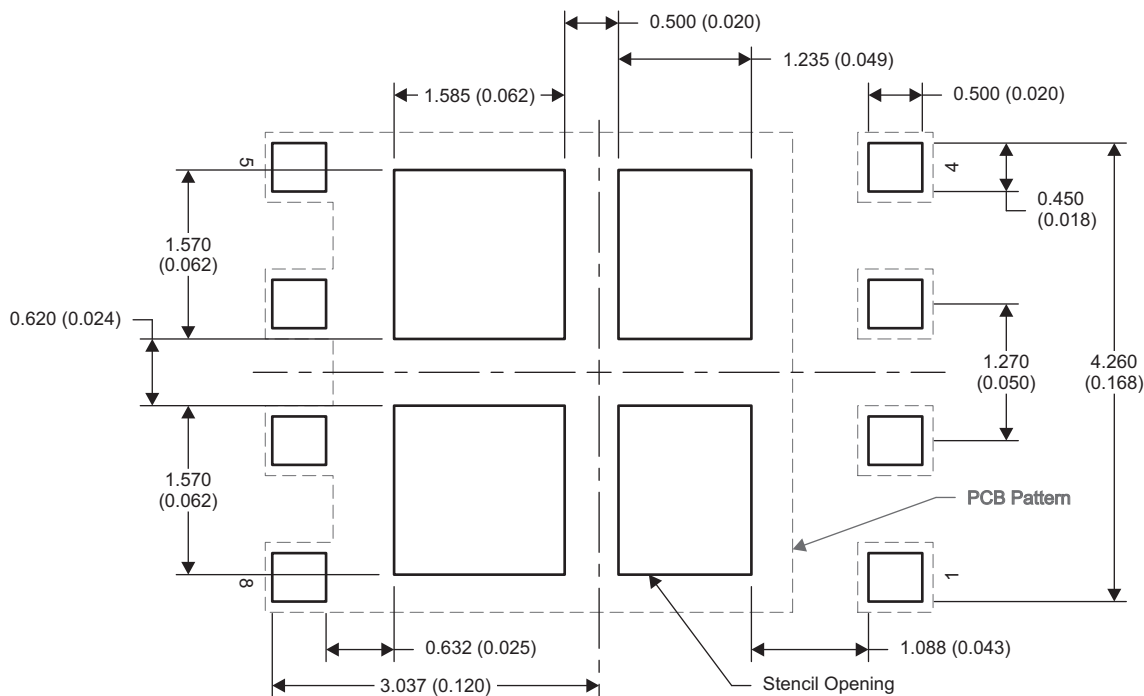
Recommended PCB Pattern



M0139-01

NOTE: Dimensions are in mm (inches).

Stencil Recommendation

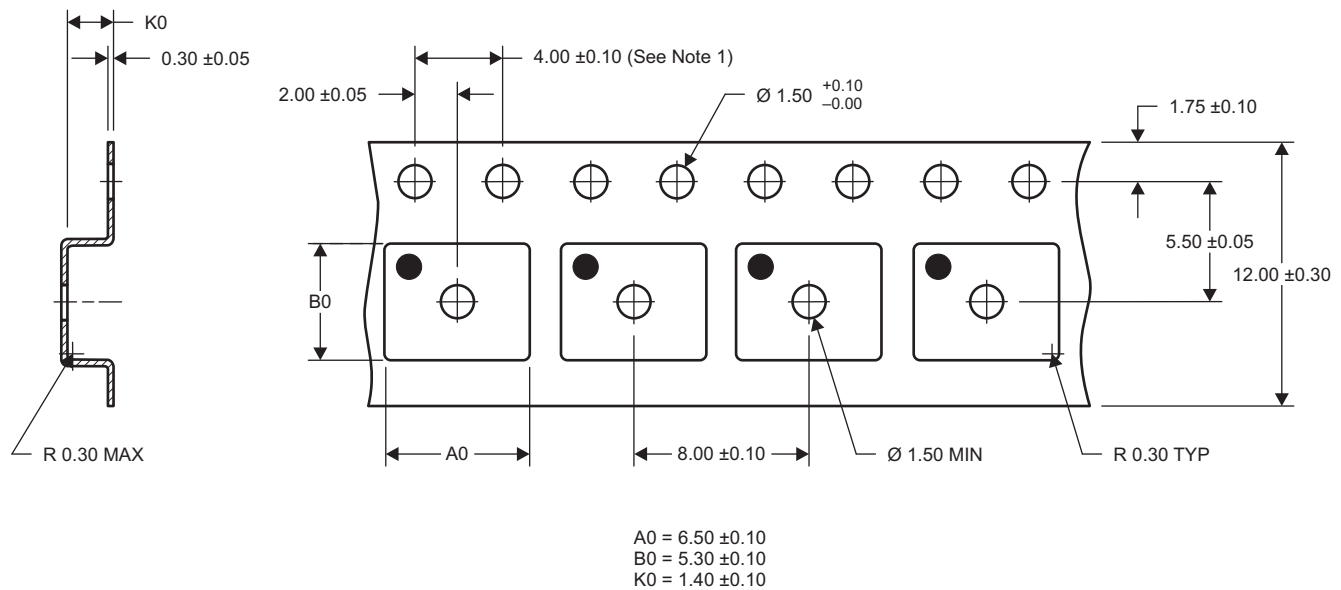


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NOTE: Dimensions are in mm (inches).

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

Q5A Tape and Reel Information



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- NOTES:
1. 10-sprocket hole-pitch cumulative tolerance ± 0.2
 2. Camber not to exceed 1mm in 100mm, noncumulative over 250mm
 3. Material: black static-dissipative polystyrene
 4. All dimensions are in mm (unless otherwise specified)
 5. A0 and B0 measured on a plane 0.3mm above the bottom of the pocket

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD17555Q5A	ACTIVE	VSONP	DQJ	8	2500	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM	-55 to 150	CSD17555	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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